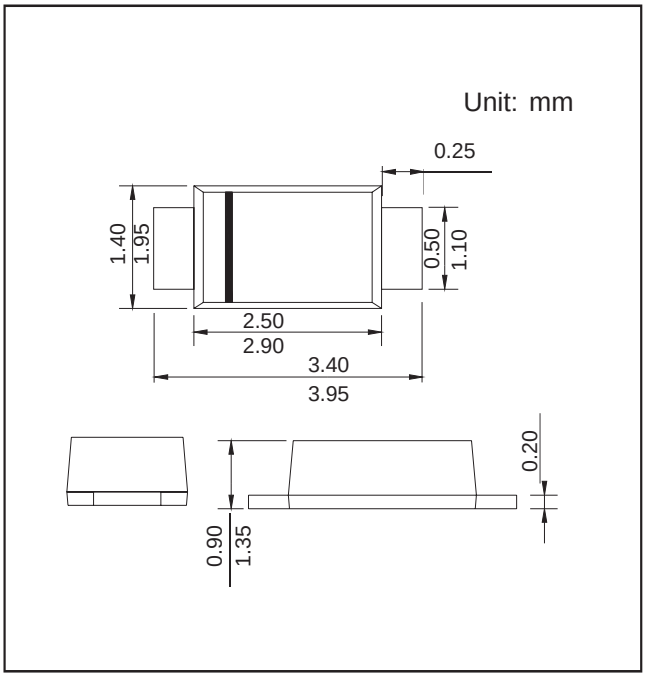
62')/

- ●For surface mounted application
- ●Glass passivated device
- ●Low forward voltage drop
- ●High current capability
- ●Easy pick and place
- ●Plastic materal used carriers Underwriters Laboratory Classification 94V-O
- ●High temperature soldering guaranteed: 250 C/10 seconds
- ●Case : JEDEC SOD-123FL molded plastic bodyover
- ●passivated chip
- ●Terminals: Plated axial leads, solderable per MIL-STD-750,Method 2026
- ●Polarity: Color band denotes cathode end Mounting Position: Any



@ 25°C Ambient Temperature (unless otherwise noted)

Parameter	Symbols	A1	A2	A3	A4	A5	A6	A7	Unis
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	Volts
Maximum average Forward Rectified Current 0.375"(9.5mm) lead length at T_A=75 C	$I_{(AV)}$	1.0							Amp
Peak Forward Surge Current (8.3ms half sine-wave superimposed on rated load (JEDEC method) T_A=75 C	I_{FSM}	30.0							Amps
Maximum Instantaneous Forward Voltage at 1A	V_F	1.0							Volts
Maximum Reverse current at rated DC Blocking Voltage T_A=25 C	I_R	5.0							μA
T_A=100 C		50.0							
Typical Thermal resistance (Note 2)	$R_{\theta JA}$	65.0							°C/W
Typical Junction Capacitance (Note 1)	C_J	10.0							pF
Maximum DC Blocking Voltage	T_A	+150							°C
temperature Operating and Storage temperature Range	T_J T_{STG}	-55 to+150							°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V DC.

2. Thermal resistance from junction to ambient and from junction to lead at 0.375"(9.5mm) lead length, P.C.B. mounted

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